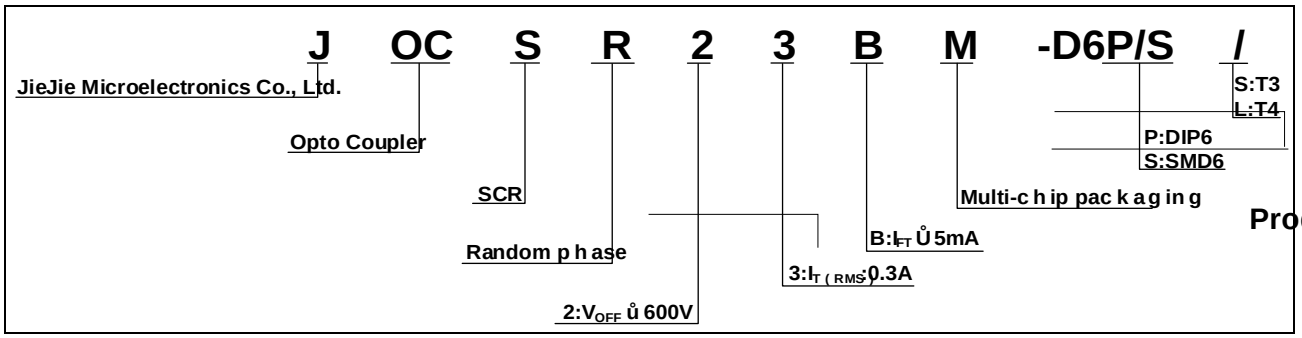
Isolation Voltage	V_{iso}	5000	Vrms
Operating Temperature	T_{opr}	-40 ~ 110	℃
Junction Temperature	T_j	125	℃
Storage Temperature	T_{stg}	-40 ~ 125	℃
Soldering Temperature	T_{sol}	260	℃
Peak pulse voltage (T=25℃ ; non-repetitive,off-state)	V_{pp}	3	kV

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FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

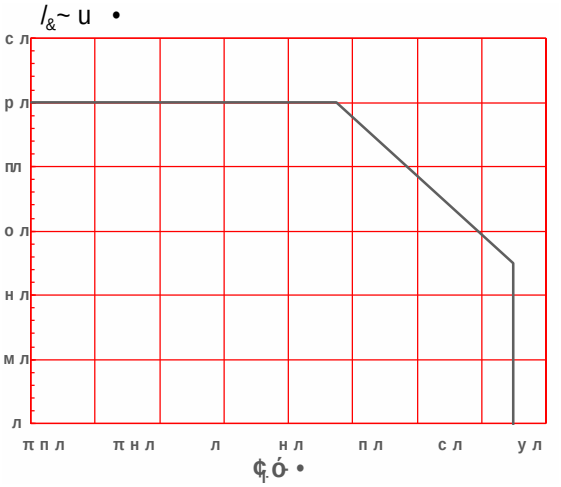


FIG.2: On-state Terminal Current vs. Ambient Temperature

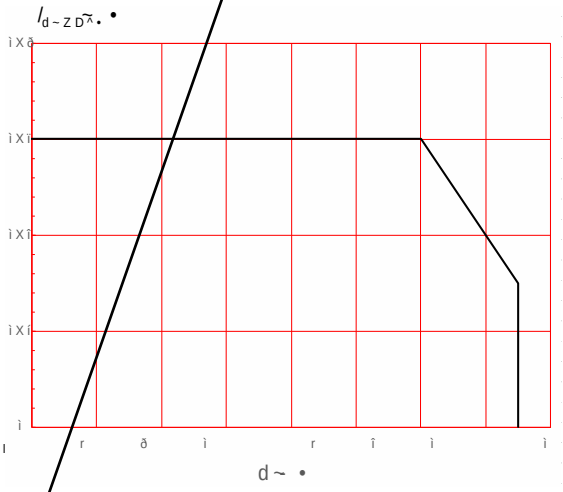


FIG.7: On-state c h aracteristics

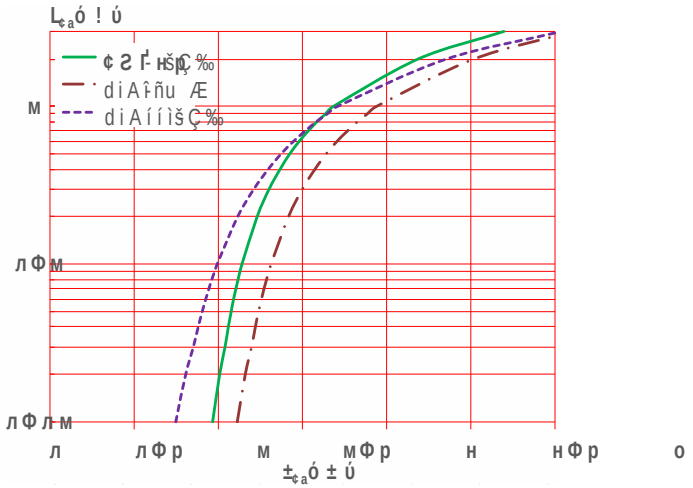


FIG.8: Normali z ed H oldin g Current vs. Ambient Temperature

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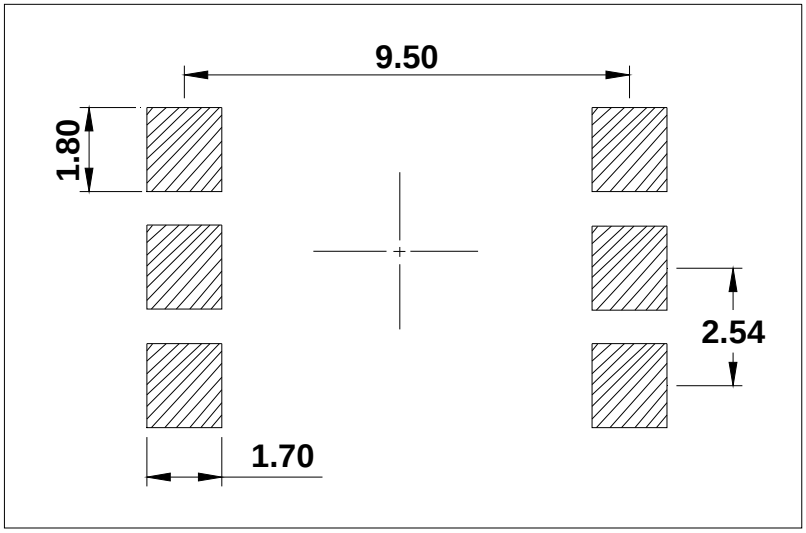
FIG.10: Test Circuits of Turn On Time

FIG.11: Waveforms of Turn On Time

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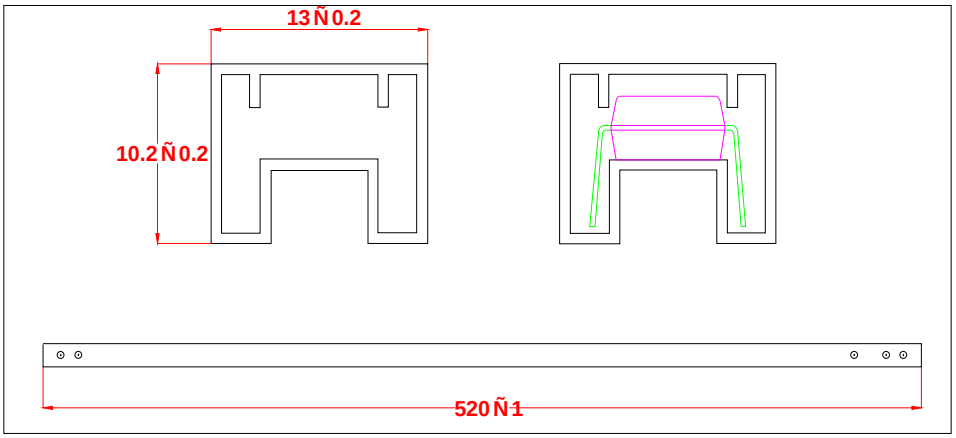
w9/haa9b595 { h [59w a ! { Y ó5ƛ Y Ŝ yˊ ă ƛ ƨ yˊ ă ƛ yˊ Y Y Ŝ ƙ zýˊ f Ŝ ă ă ƨ

Option SMD



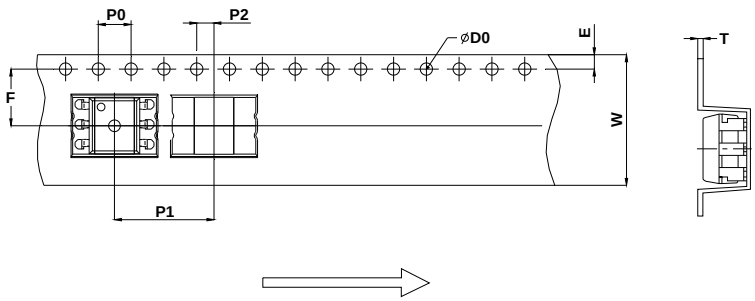
¢ ¦ .9 { t9/LCL/ ! ¢ L h b { ó5ƛ Y Ŝ yˊ ă ƛ ƨ yˊ ă ƛ yˊ Y Y dz yˊ f Ŝ ă ă ƨ ű Ƙ Ŝ

Standard DIP



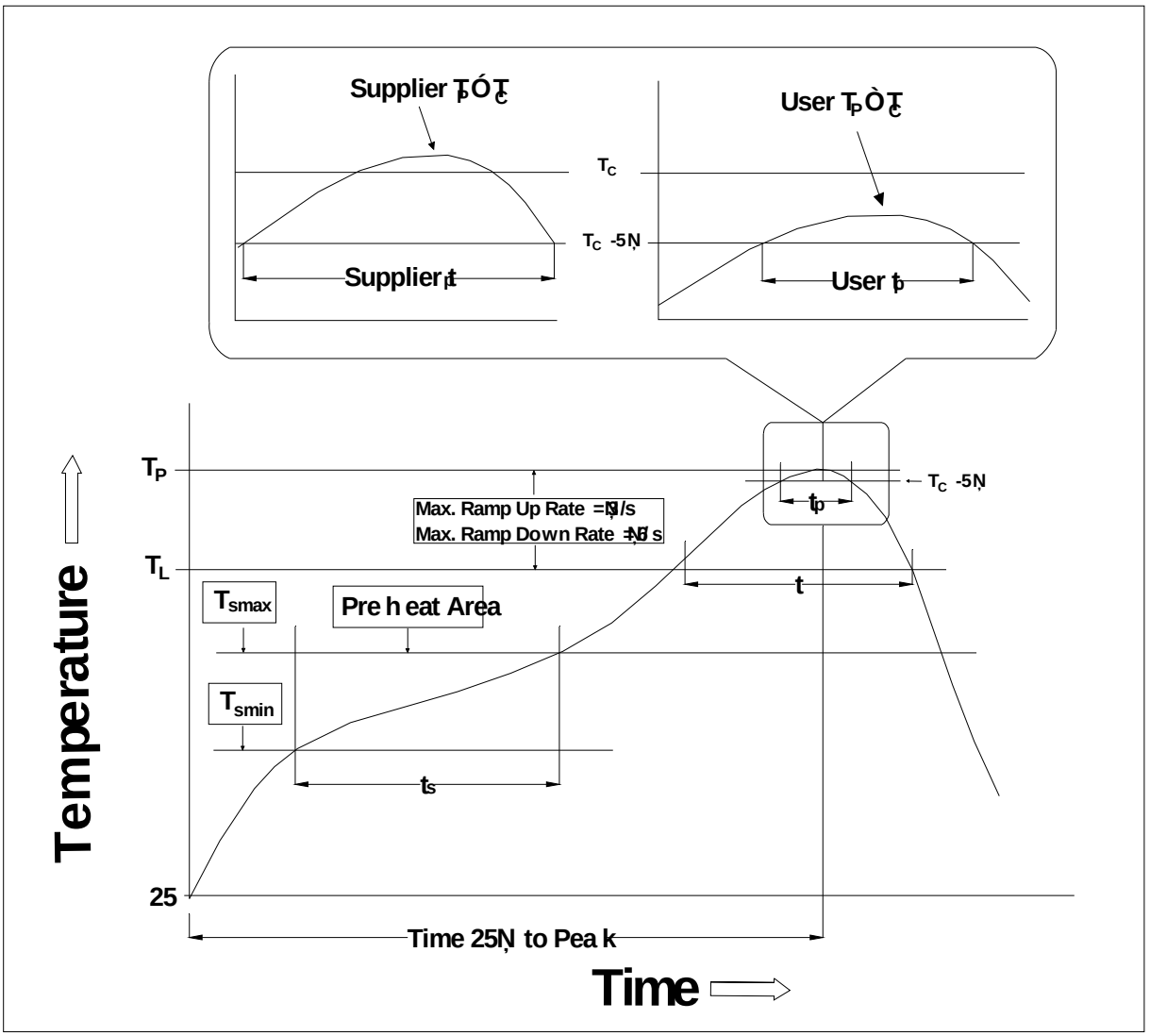
/ ! w wL9w ¢ ! t9 { t9/LCL/ ! ¢ Ŝ hyƴbă{ ƛ ó ₴5y ƛ ă ƴ ƛ y ˝ Y ˝ Y ˝ dz y ˝ ă f ú Ŝ l ă ú ă Ŝ ₴ Ř ű ü K Ŝ NJ ¢

Option S



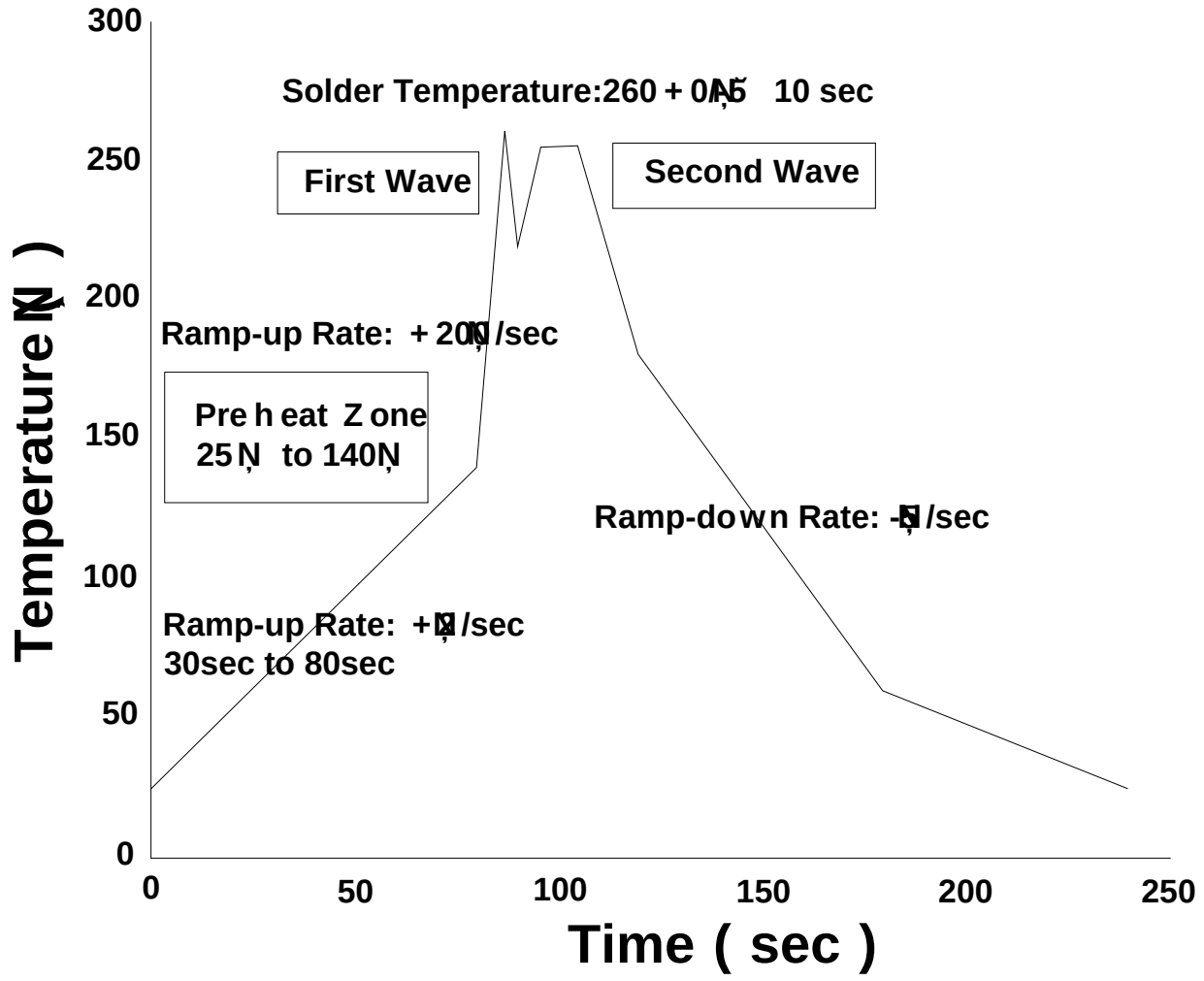
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

w9C [h ² LbC h wa ! ¢ L h b



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Li q uidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Pea k Body Pac k a g e Temperature	235 /-5	260 + 0 /-5
Time (tP) wit hin 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Pea k Temperature	6 minutes max.	8 minutes max.

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Soldering Temperature	360 ¤ 5Ņ
Soldering Time	3s max.

Note: